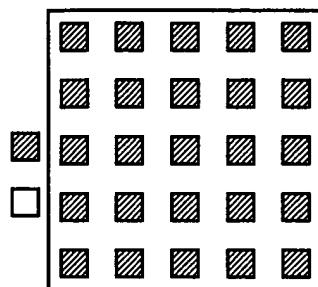


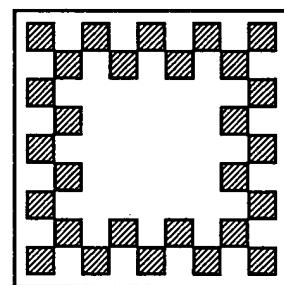


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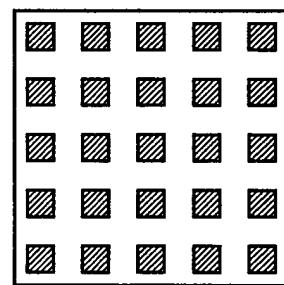
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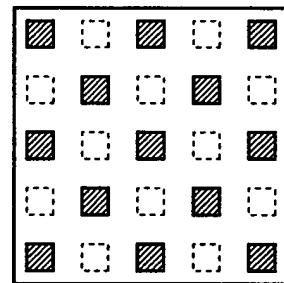
Prior Art  
**Figure 1**  
Perimeter I/O



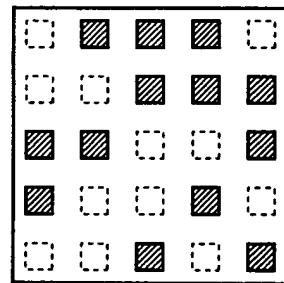
Prior Art  
**Figure 2**  
Staggered Perimeter I/O



**Figure 3**  
Full Array



**Figure 4**  
Depopulated Array



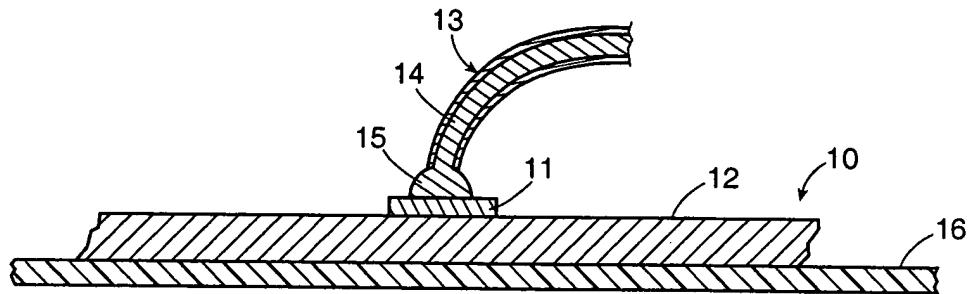
**Figure 5**  
Random Array

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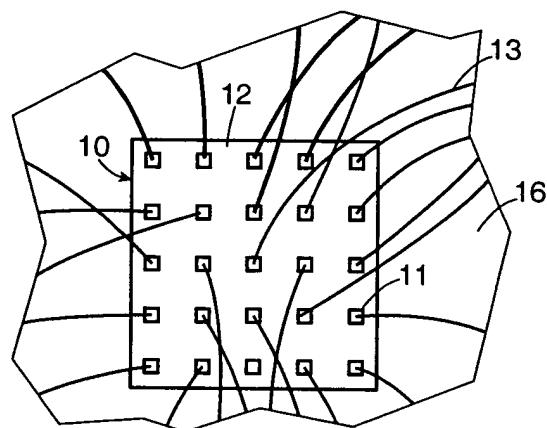
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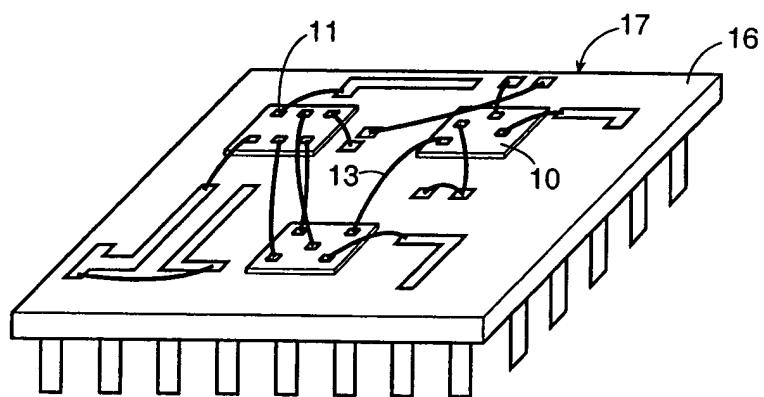
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**Figure 6**



**Figure 7**



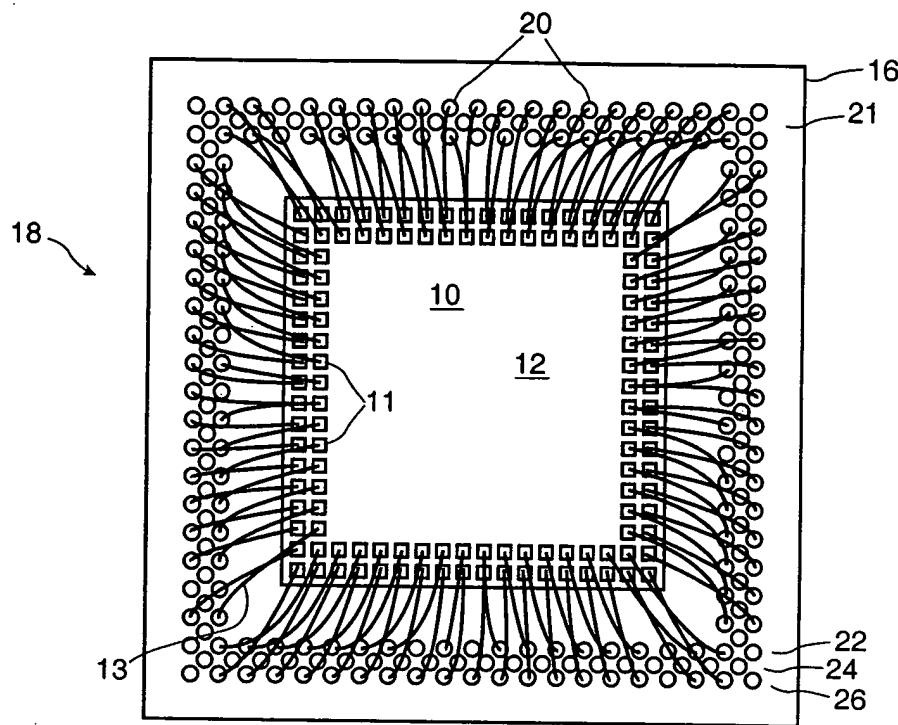
**Figure 8**

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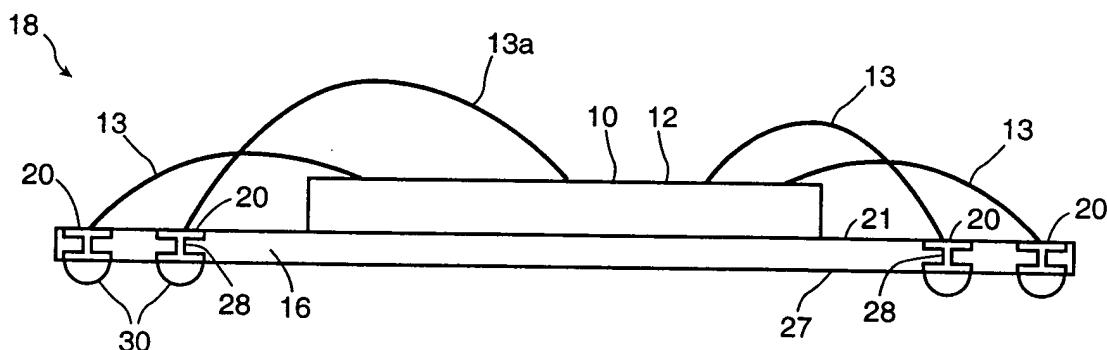
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**Figure 9**



**Figure 10**

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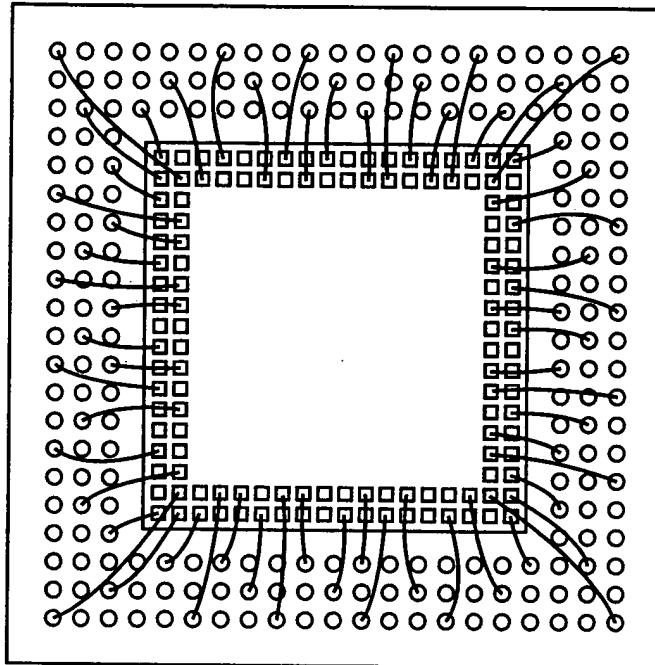


Figure 11b

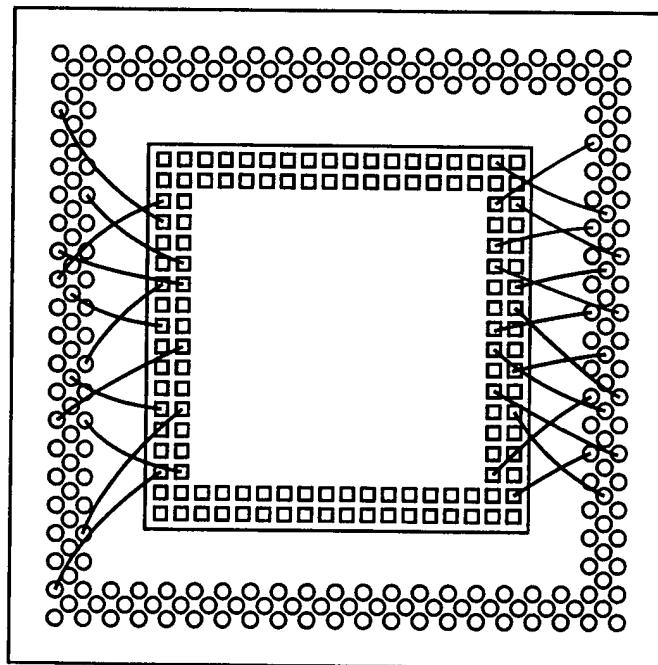


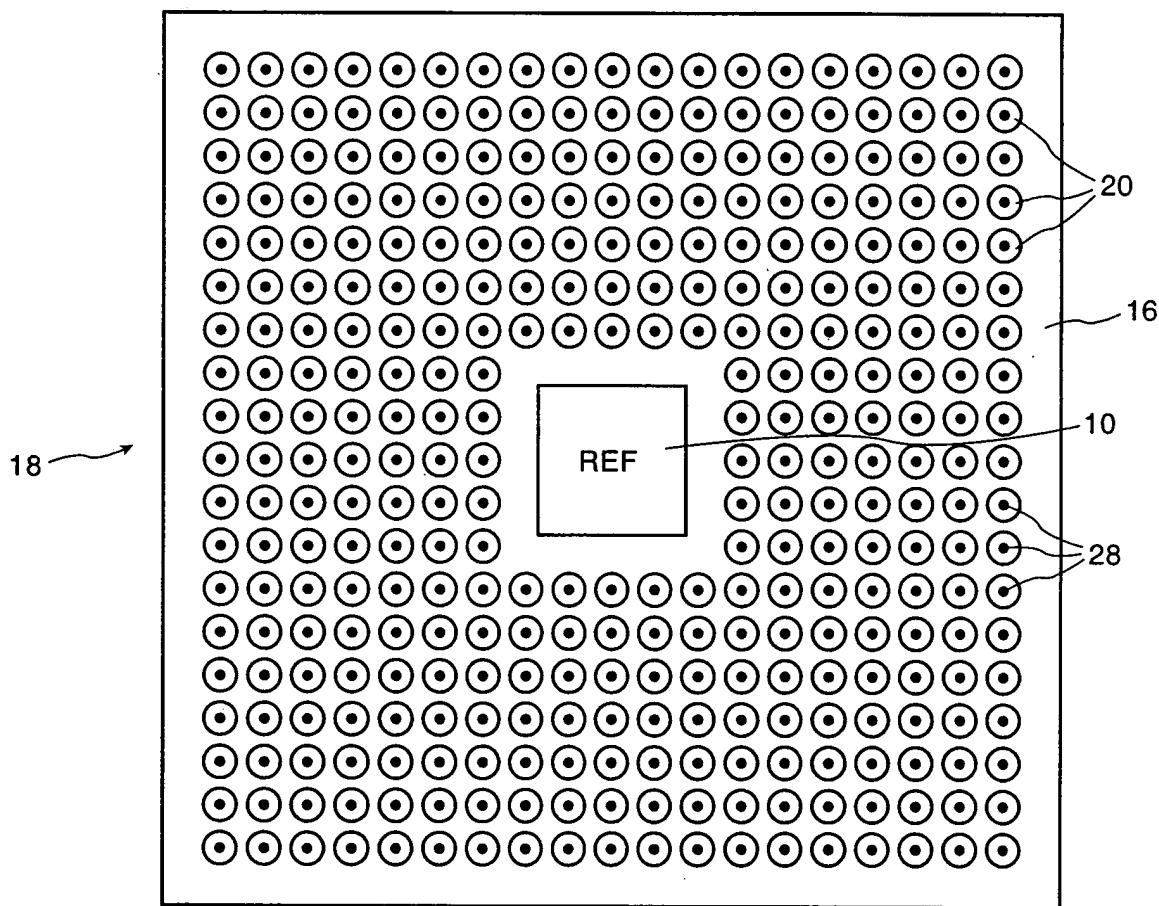
Figure 11a

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**Figure 12**